

TENTATIVE TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT SILICON GATE CMOS  
262,144-WORD BY 8-BIT FULL CMOS STATIC RAM

## DESCRIPTION

The TC55V020FT/TR is a 2,097,152-bit static random access memory (SRAM) organized as 262,144 words by 8 bits. Fabricated using Toshiba's CMOS Silicon gate process technology, this device operates from a single 2.7 to 3.6V power supply. Advanced circuit technology provides both high speed and low power at an operating current of 3 mA/MHz and a minimum cycle time of 70 ns. It is automatically placed in low-power mode at 0.5  $\mu$ A standby current (at  $V_{DD}=3V$ ,  $T_a=25^\circ C$ , maximum) when chip enable ( $\overline{CE1}$ ) is asserted high or ( $CE2$ ) is asserted low. There are three control inputs.  $\overline{CE1}$  and  $CE2$  are used to select the device and for data retention control, and output enable ( $\overline{OE}$ ) provides fast memory access. This device is well suited to various microprocessor system applications where high speed, low power and battery backup are required. And, with a guaranteed operating range of  $-40^\circ$  to  $85^\circ C$ , the TC55V020FT/TR can be used in environments exhibiting extreme temperature conditions. The TC55V020FT/TR is available in normal and reverse pinout plastic 40-pin thin-small-outline package (TSOP).

## FEATURES

- Low-power dissipation  
Operating: 10.8 mW/MHz (typical)
- Single power supply voltage of 2.7 to 3.6V
- Power down features using  $\overline{CE1}$  and  $CE2$
- Data retention supply voltage of 1.5 to 3.6V
- Direct TTL compatibility for all inputs and outputs
- Wide operating temperature range of  $-40^\circ$  to  $85^\circ C$
- Standby current (maximum)

3.6V	7 $\mu$ A
3.0V	5 $\mu$ A

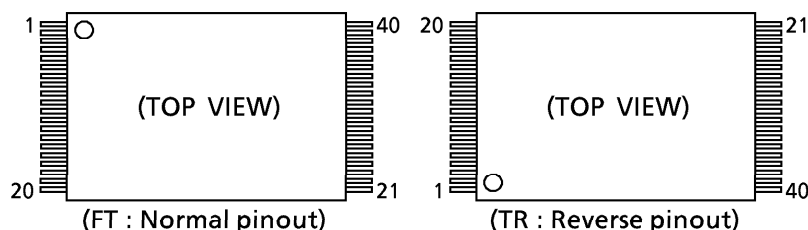
- Access Times (maximum):

	TC55V020FT/TR		
	-70	-85	-10
Access Time	70 ns	85 ns	100 ns
CE1 Access Time	70 ns	85 ns	100 ns
CE2 Access Time	70 ns	85 ns	100 ns
$\overline{OE}$ Access Time	35 ns	45 ns	50 ns

- Package:

TSOP I 40-P-1014-0.50 (FT) (Weight:0.32g typ)  
TSOP I 40-P-1014-0.50A (TR) (Weight:0.32g typ)

## PIN ASSIGNMENT (TOP VIEW)



## PIN NAMES

A0 to A17	Address Inputs
$\overline{CE1}$ , $CE2$	Chip Enable Input
R/W	Read / Write Control Input
$\overline{OE}$	Output Enable Input
I/O1 to I/O8	Data Inputs / Outputs
$V_{DD}$	Power
GND	Ground
NC	No Connection

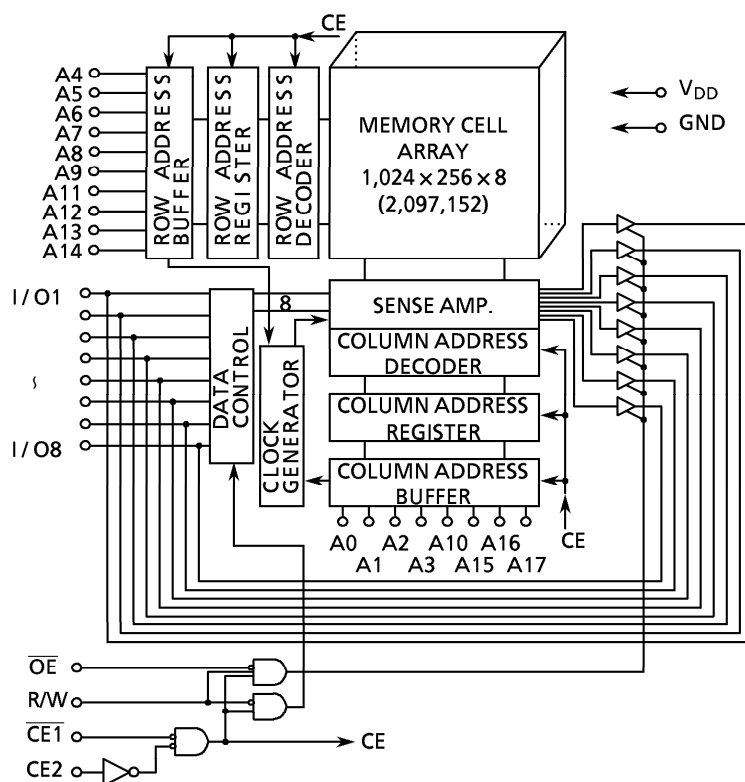
## (TSOP)

Pin No.	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
Pin Name	A16	A15	A14	A13	A12	A11	A9	A8	R/W	CE2	NC	NC	NC	A7	A6	A5	A4	A3	A2	A1
Pin No.	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	37	38	39	40
Pin Name	A0	$\overline{CE1}$	GND	$\overline{OE}$	I/O1	I/O2	I/O3	I/O4	NC	$V_{DD}$	$V_{DD}$	I/O5	I/O6	I/O7	I/O8	A10	NC	NC	GND	A17

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**BLOCK DIAGRAM**



**OPERATING MODE**

MODE	$\overline{CE1}$	CE2	$\overline{OE}$	R/W	I/O1 to I/O8	POWER
Read	L	H	L	H	D <sub>OUT</sub>	I <sub>DDO</sub>
Write	L	H	x	L	D <sub>IN</sub>	I <sub>DDO</sub>
Output Deselect	L	H	H	H	High-Z	I <sub>DDO</sub>
Standby	H	x	x	x	High-Z	I <sub>DDS</sub>
	x	L	x	x	High-Z	I <sub>DDS</sub>

Note: x = don't care. H = logic high. L = logic low.

**MAXIMUM RATINGS**

SYMBOL	RATING	VALUE	UNIT
V <sub>DD</sub>	Power Supply Voltage	- 0.3 to 4.6	V
V <sub>IN</sub>	Input Voltage	- 0.3 * to 4.6	V
V <sub>I/O</sub>	Input/Output Voltage	- 0.5 to V <sub>DD</sub> + 0.5	V
P <sub>D</sub>	Power Dissipation	0.6	W
T <sub>solder</sub>	Soldering Temperature (10 s)	260	°C
T <sub>strg</sub>	Storage Temperature	- 55 to 150	°C
T <sub>opr</sub>	Operating Temperature	- 40 to 85	°C

\* - 3.0 V when measured at a pulse width of 30 ns.

**DC RECOMMENDED OPERATING CONDITIONS (Ta = -40° to 85°C)**

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>DD</sub>	Power Supply Voltage	2.7	-	3.6	V
V <sub>IH</sub>	Input High Voltage	2.2	-	V <sub>DD</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage	- 0.3 *	-	0.6	V
V <sub>DH</sub>	Data Retention Supply Voltage	1.5	-	3.6	V

\* - 3.0 V when measured at a pulse width of 30 ns.

**DC CHARACTERISTICS (Ta = -40° to 85°C, V<sub>DD</sub> = 2.7 to 3.6V)**

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT			
I <sub>IL</sub>	Input Leakage Current	V <sub>IN</sub> = 0 V to V <sub>DD</sub>	-	-	± 1.0	μA			
I <sub>OH</sub>	Output High Current	V <sub>OH</sub> = V <sub>DD</sub> - 0.5 V	- 0.5	-	-	mA			
I <sub>OL</sub>	Output Low Current	V <sub>OL</sub> = 0.4 V	2.1	-	-	mA			
I <sub>LO</sub>	Output Leakage Current	CE1 = V <sub>IH</sub> or CE2 = V <sub>IL</sub> or R/W = V <sub>IL</sub> or OE = V <sub>IH</sub> V <sub>OUT</sub> = 0 V to V <sub>DD</sub>	-	-	± 1.0	μA			
I <sub>DDO1</sub>	Operating Current	CE1 = V <sub>IL</sub> and CE2 = V <sub>IH</sub> and R/W = V <sub>IH</sub> and I <sub>OUT</sub> = 0 mA Other Input = V <sub>IH</sub> /V <sub>IL</sub>	V <sub>DD</sub> = 3 V ± 10%	Tcycle = min	-70	-	-	40	mA
				-85,-10	-	-	35		
		V <sub>DD</sub> = 3.3 V ± 0.3 V	Tcycle = 1 μs	-	-	10			
			Tcycle = min	-70	-	-	45		
I <sub>DDO2</sub>	Operating Current	CE1 = 0.2 V and CE2 = V <sub>DD</sub> - 0.2 V and R/W = V <sub>DD</sub> - 0.2 V, I <sub>OUT</sub> = 0 mA Other Inputs = V <sub>DD</sub> - 0.2V/0.2V	V <sub>DD</sub> = 3 V ± 10%	Tcycle = min	-70	-	-	35	
				-85,-10	-	-	30		
		V <sub>DD</sub> = 3.3 V ± 0.3 V	Tcycle = 1 μs	-	-	5			
			Tcycle = min	-70	-	-	40		
I <sub>DDS1</sub>	Standby Current	CE1 = V <sub>IH</sub> or CE2 = V <sub>IL</sub>	V <sub>DD</sub> = 3 V ± 10%	Tcycle = min	-70	-	-	40	
				-85,-10	-	-	35		
I <sub>DDS2</sub> (Note)	Standby Current	CE1 = V <sub>DD</sub> - 0.2 V or CE2 = 0.2 V V <sub>DD</sub> = 1.5 to 3.6 V	V <sub>DD</sub> = 3.3 V ± 0.3 V	Tcycle = 1 μs	-	-	-	6	
				Ta = 25°C	-	-	0.6		
				Ta = -40 to 85°C	-	-	6		
				Ta = 25°C	-	-	0.7		
I <sub>DDS2</sub> (Note)	Standby Current	CE1 = V <sub>DD</sub> - 0.2 V or CE2 = 0.2 V V <sub>DD</sub> = 1.5 to 3.6 V	V <sub>DD</sub> = 3.3 V ± 0.3 V	Ta = -40 to 85°C	-	-	-	7	
				Ta = 25°C	-	0.05	0.5		
				Ta = -40 to 40°C	-	-	1		
				Ta = -40 to 85°C	-	-	5		

Note: In standby mode with CE1 ≥ V<sub>DD</sub> - 0.2V, these limits are assured for the condition CE2 ≥ V<sub>DD</sub> - 0.2V or CE2 ≤ 0.2V.

**CAPACITANCE (Ta = 25°C, f = 1 MHz)**

SYMBOL	PARAMETER	TEST CONDITION	MAX	UNIT
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = GND	10	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = GND	10	pF

Note: This parameter is periodically sampled and is not 100% tested.

**AC CHARACTERISTICS AND OPERATING CONDITIONS (Ta = -40° to 85°C, V<sub>DD</sub> = 2.7 to 3.6V)**

**READ CYCLE**

SYMBOL	PARAMETER	TC55V020FT/TR						UNIT
		-70		-85		-10		
		MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>RC</sub>	Read Cycle Time	70	–	85	–	100	–	ns
t <sub>ACC</sub>	Address Access Time	–	70	–	85	–	100	
t <sub>CO1</sub>	Chip Enable (CE1) Access Time	–	70	–	85	–	100	
t <sub>CO2</sub>	Chip Enable (CE2) Access Time	–	70	–	85	–	100	
t <sub>OE</sub>	Output Enable Access Time	–	35	–	45	–	50	
t <sub>COE</sub>	Chip Enable Low to Output Active	5	–	5	–	5	–	
t <sub>OEE</sub>	Output Enable Low to Output Active	0	–	0	–	0	–	
t <sub>OD</sub>	Chip Enable High to Output High-Z	–	30	–	35	–	40	
t <sub>ODO</sub>	Output Enable High to Output High-Z	–	30	–	35	–	40	
t <sub>OH</sub>	Output Data Hold Time	10	–	10	–	10	–	

**WRITE CYCLE**

SYMBOL	PARAMETER	TC55V020FT/TR						UNIT
		-70		-85		-10		
		MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>WC</sub>	Write Cycle Time	70	–	85	–	100	–	ns
t <sub>WP</sub>	Write Pulse Width	50	–	55	–	60	–	
t <sub>CW</sub>	Chip Enable to End of Write	60	–	70	–	80	–	
t <sub>AS</sub>	Address Setup Time	0	–	0	–	0	–	
t <sub>WR</sub>	Write Recovery Time	0	–	0	–	0	–	
t <sub>ODW</sub>	R/W Low to Output High-Z	–	30	–	35	–	40	
t <sub>OEW</sub>	R/W High to Output Active	0	–	0	–	0	–	
t <sub>DS</sub>	Data Setup Time	30	–	35	–	40	–	
t <sub>DH</sub>	Data Hold Time	0	–	0	–	0	–	

**AC TEST CONDITIONS**

Output load: 30 pF + one TTL gate (-70)

: 100 pF + one TTL gate (-85, -10)

Input pulse level: 0.4 V, 2.4 V

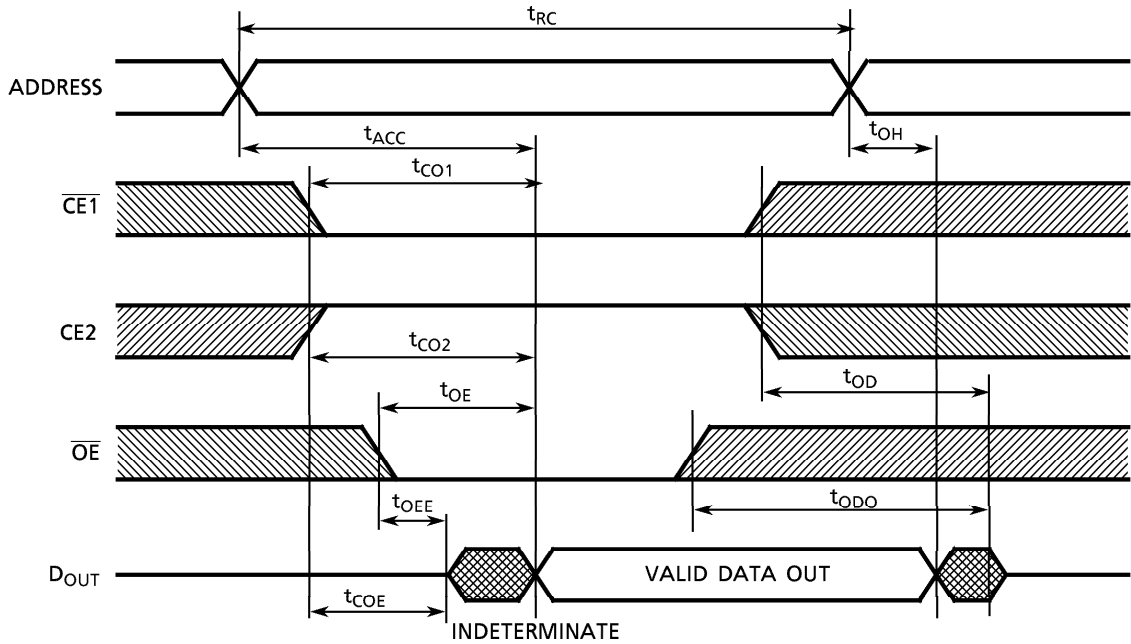
Timing measurements: 1.5 V

Reference level: V<sub>DD</sub> × 0.5

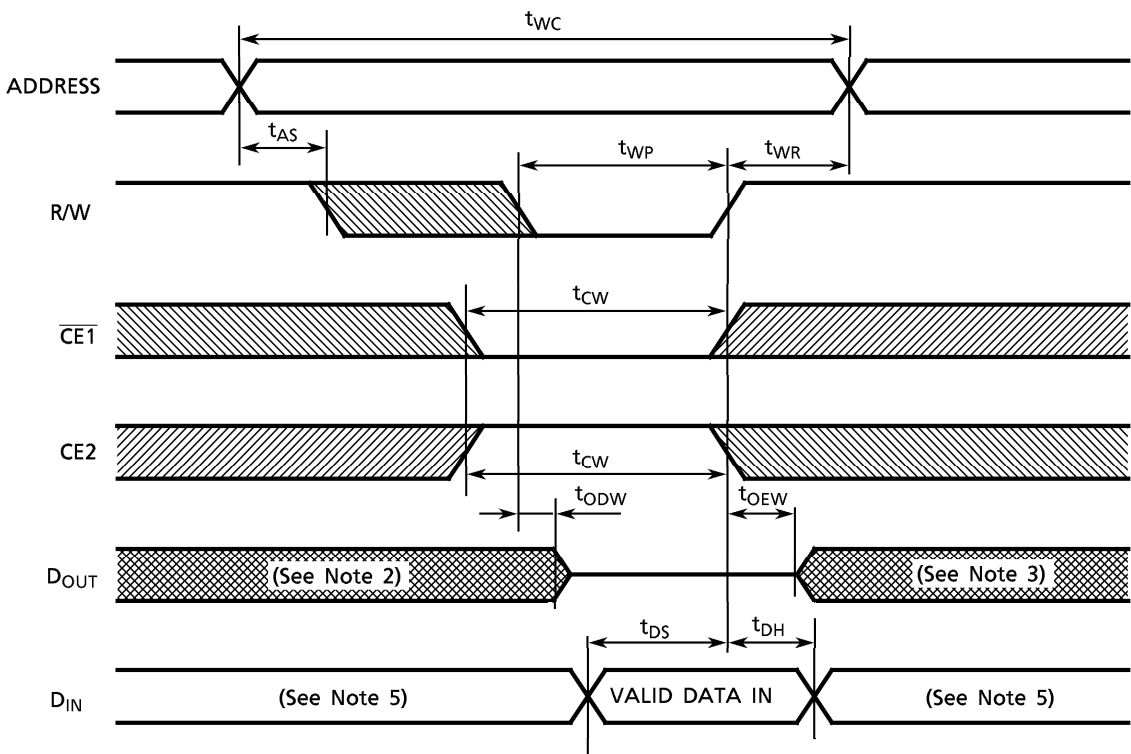
t<sub>R</sub>, t<sub>F</sub>: 5 ns

**TIMING DIAGRAMS**

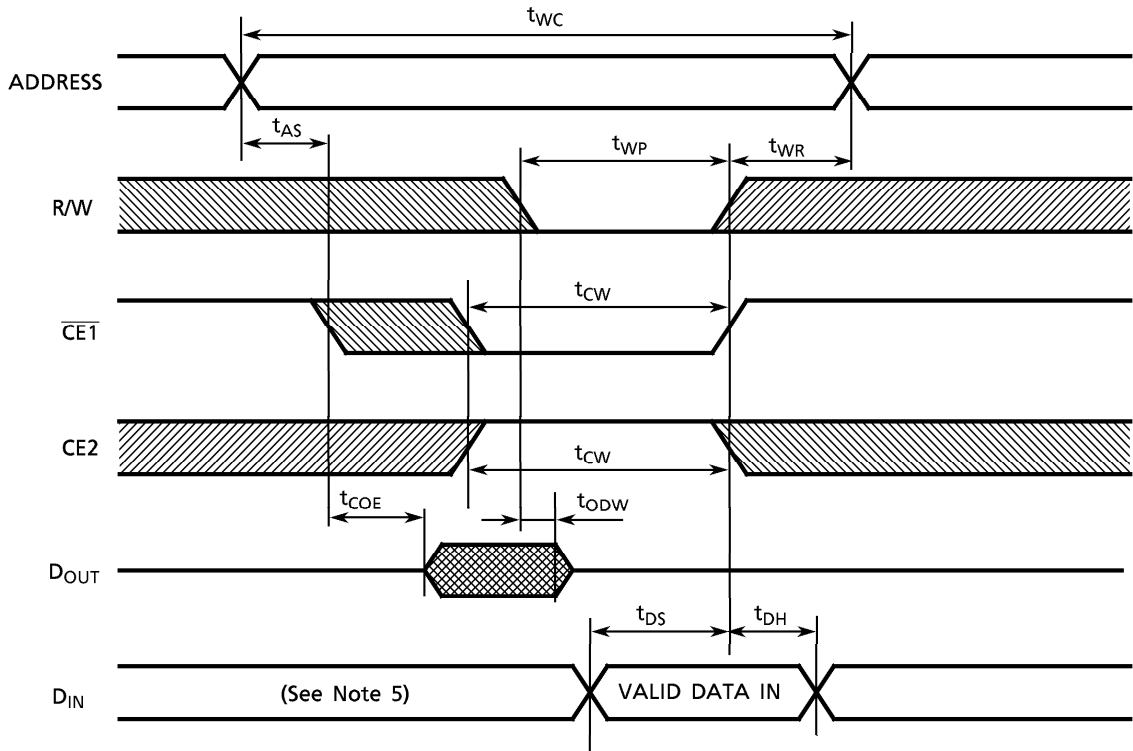
**READ CYCLE (See Note 1)**



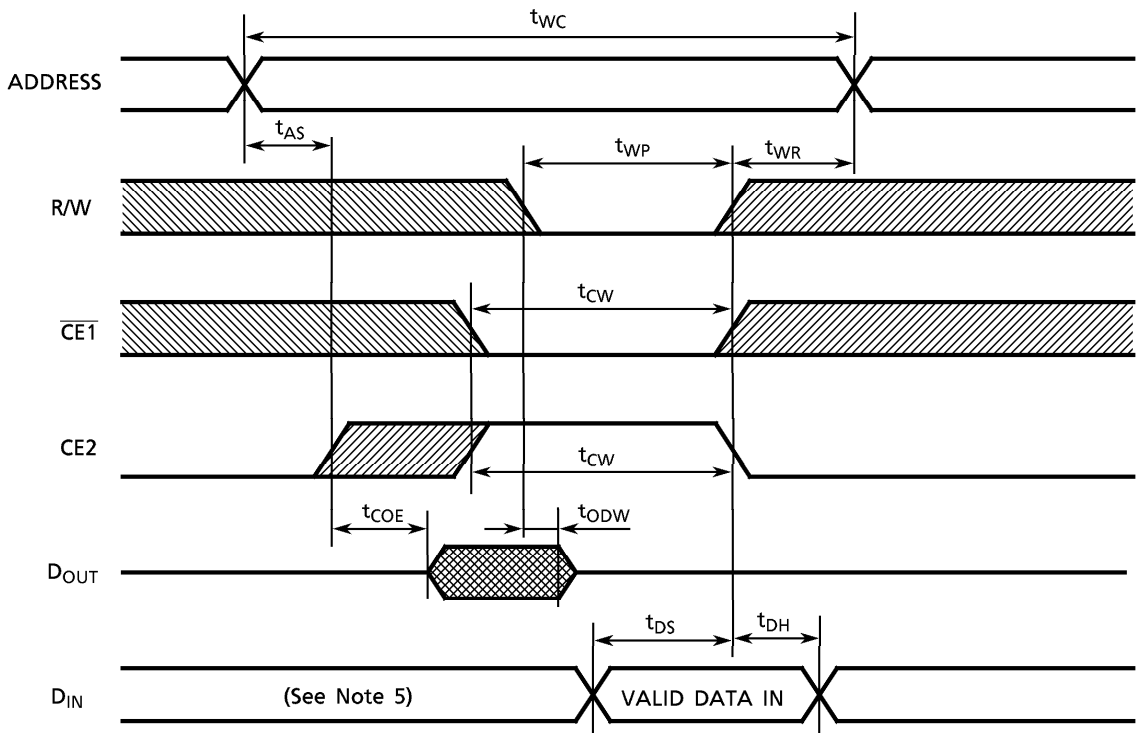
**WRITE CYCLE 1 (R/W CONTROLLED) (See Note 4)**



WRITE CYCLE 2 (CE1 CONTROLLED) (See Note 4)



WRITE CYCLE 3 (CE2 CONTROLLED) (See Note 4)



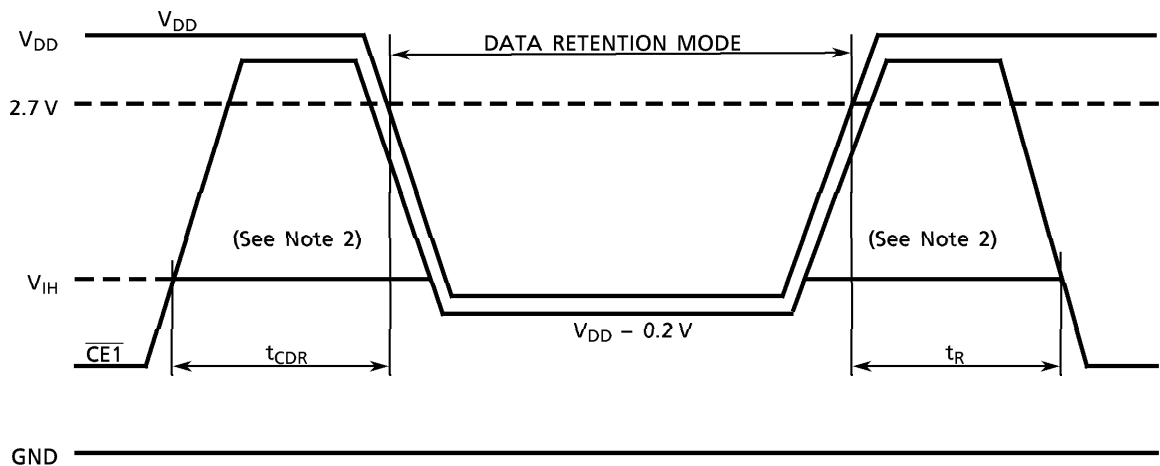
- Note:
- (1) R/W remains HIGH for the read cycle.
  - (2) If  $\overline{CE1}$  goes LOW (or CE2 goes HIGH) coincident with or after R/W goes LOW, the outputs will remain at high impedance.
  - (3) If  $\overline{CE1}$  goes HIGH (or CE2 goes LOW) coincident with or before R/W goes HIGH, the outputs will remain at high impedance.
  - (4) If  $\overline{OE}$  is HIGH during the write cycle, the outputs will remain at high impedance.
  - (5) Because I/O signals may be in the output state at this time, input signals of reverse polarity must not be applied.

**DATA RETENTION CHARACTERISTICS (Ta = -40° to 85°C)**

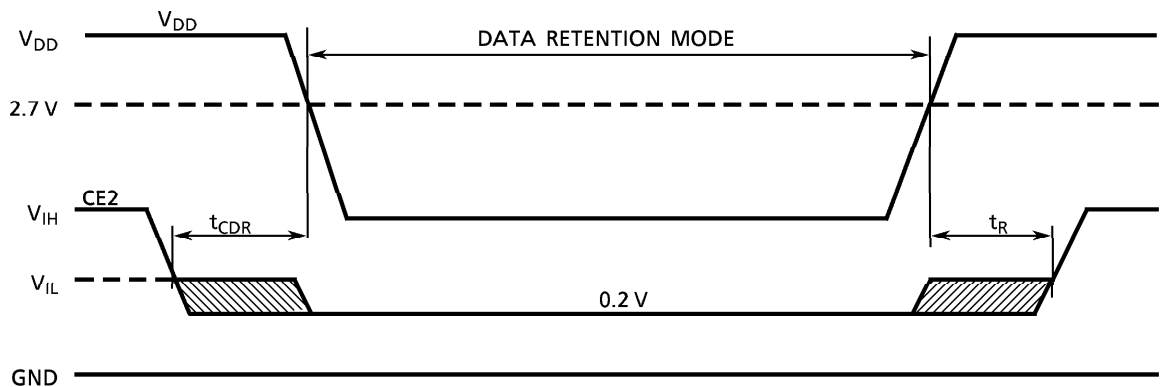
SYMBOL	PARAMETER		MIN	TYP	MAX	UNIT	
$V_{DH}$	Data Retention Supply Voltage		1.5	-	3.6	V	
$I_{DSS2}$	Standby Current	$V_{DH} = 3.0\text{ V}$	$T_a = -40^\circ\text{ to }40^\circ\text{C}$	-	-	1	$\mu\text{A}$
			$T_a = -40^\circ\text{ to }85^\circ\text{C}$	-	-	5	
		$V_{DH} = 3.6\text{ V}$	$T_a = -40^\circ\text{ to }85^\circ\text{C}$	-	-	7	
$t_{CDR}$	Chip Deselect to Data Retention Mode Time		0	-	-	nS	
$t_R$	Recovery Time		$t_{RC}$ (See Note)	-	-	nS	

Note: Read cycle time

**$\overline{CE1}$  CONTROLLED DATA RETENTION MODE (See Note 1)**



**CE2 CONTROLLED DATA RETENTION MODE (See Note 3)**

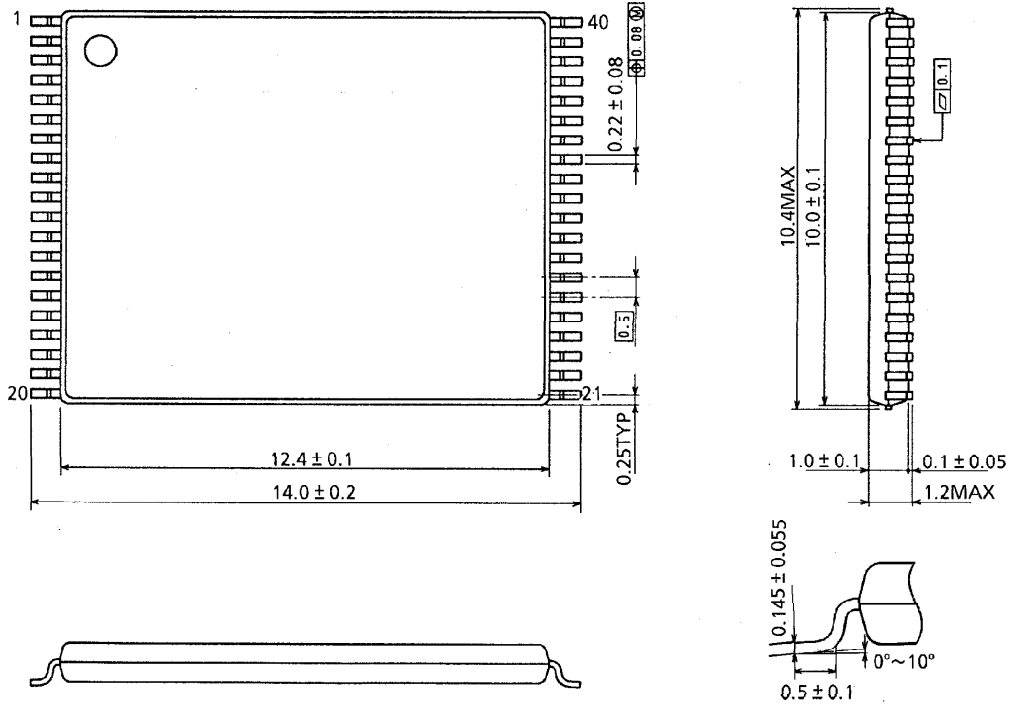


- Note:
- (1) In  $\overline{\text{CE1}}$  controlled data retention mode, minimum standby current mode is entered when  $\text{CE2} \leq 0.2 \text{ V}$  or  $\text{CE2} \geq \text{V}_{\text{DD}} - 0.2 \text{ V}$ .
  - (2) When  $\overline{\text{CE1}}$  is operating at the  $\text{V}_{\text{IH}}$  level (2.2 V), the operating current is given by  $\text{I}_{\text{DDSI}}$  during the transition of  $\text{V}_{\text{DD}}$  from 3.6 to 2.4 V.
  - (3) In  $\text{CE2}$  controlled data retention mode, minimum standby current mode is entered when  $\text{CE2} \leq 0.2 \text{ V}$ .



PACKAGE DIMENSIONS (TSOP I 40-P-1014-0.50)

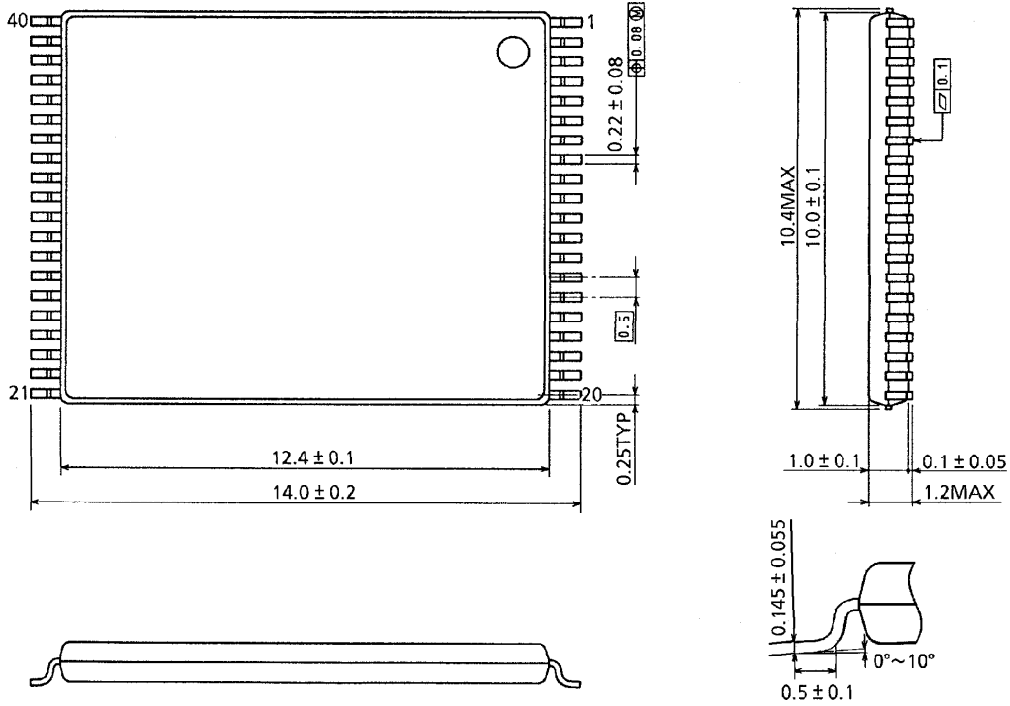
Units in mm



Weight: 0.32 g (typ)

PACKAGE DIMENSIONS (TSOP I 40-P-1014-0.5A)

Units in mm



Weight: 0.32 g (typ)